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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

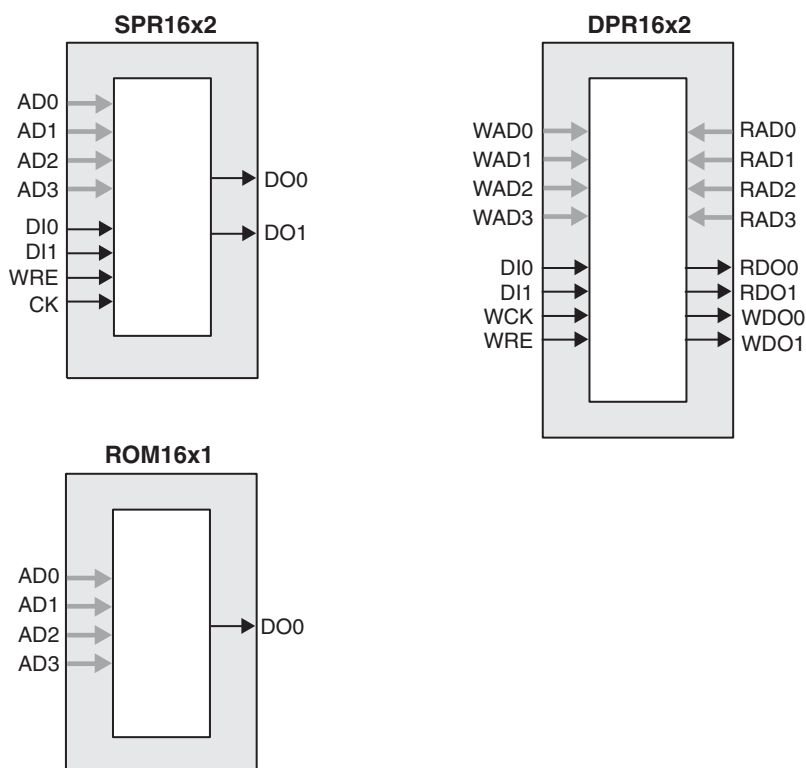
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	80
Number of Logic Elements/Cells	640
Total RAM Bits	-
Number of I/O	159
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640c-4ft256i

Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

The EBR memory supports three forms of write behavior for single or dual port operation:

1. **Normal** – data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
2. **Write Through** – a copy of the input data appears at the output of the same port. This mode is supported for all data widths.
3. **Read-Before-Write** – when new data is being written, the old contents of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

FIFO Configuration

The FIFO has a write port with Data-in, CEW, WE and CLKW signals. There is a separate read port with Data-out, RCE, RE and CLKR signals. The FIFO internally generates Almost Full, Full, Almost Empty and Empty Flags. The Full and Almost Full flags are registered with CLKW. The Empty and Almost Empty flags are registered with CLKR. The range of programming values for these flags are in Table 2-7.

Table 2-7. Programmable FIFO Flag Ranges

Flag Name	Programming Range
Full (FF)	1 to (up to 2^N-1)
Almost Full (AF)	1 to Full-1
Almost Empty (AE)	1 to Full-1
Empty (EF)	0

N = Address bit width

The FIFO state machine supports two types of reset signals: RSTA and RSTB. The RSTA signal is a global reset that clears the contents of the FIFO by resetting the read/write pointer and puts the FIFO flags in their initial reset state. The RSTB signal is used to reset the read pointer. The purpose of this reset is to retransmit the data that is in the FIFO. In these applications it is important to keep careful track of when a packet is written into or read from the FIFO.

Memory Core Reset

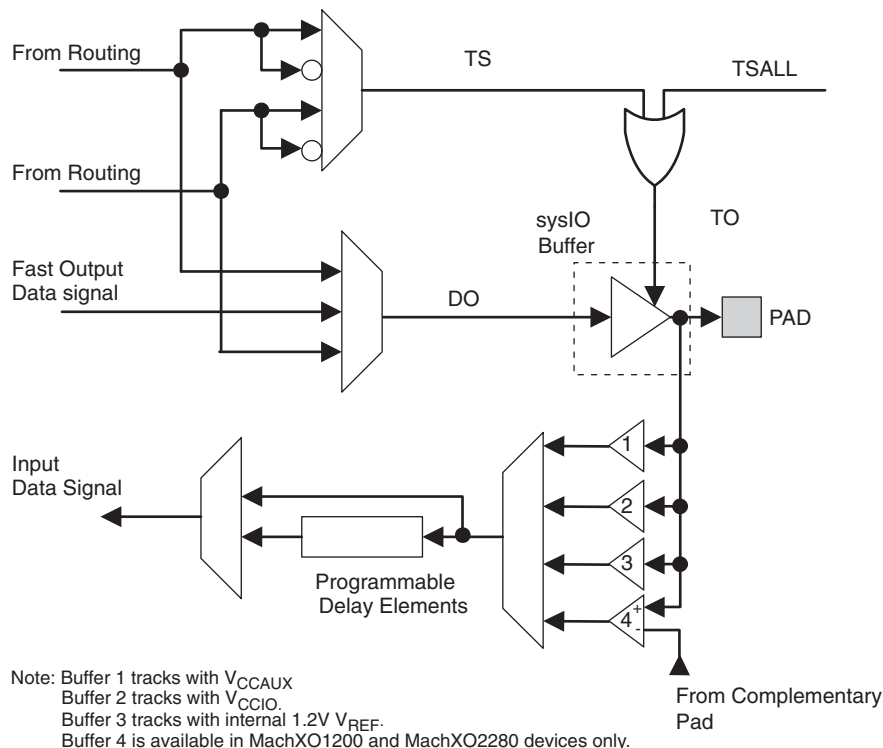
The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-13.

output data signals are multiplexed and provide a single signal to the I/O pin via the sysIO buffer. Figure 2-17 shows the MachXO PIO logic.

The tristate control signal is multiplexed from the output data signals and their complements. In addition a global signal (TSALL) from a dedicated pad can be used to tristate the sysIO buffer.

The PIO receives an input signal from the pin via the sysIO buffer and provides this signal to the core of the device. In addition there are programmable elements that can be utilized by the design tools to avoid positive hold times.

Figure 2-17. MachXO PIO Block Diagram



sysIO Buffer

Each I/O is associated with a flexible buffer referred to as a sysIO buffer. These buffers are arranged around the periphery of the device in groups referred to as Banks. The sysIO buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, TTL, BLVDS, LVDS and LVPECL.

In the MachXO devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS and PCI) are powered using V_{CCIO} . In addition to the Bank V_{CCIO} supplies, the MachXO devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that powers up a variety of internal circuits including all the differential and referenced input buffers.

MachXO256 and MachXO640 devices contain single-ended input buffers and single-ended output buffers with complementary outputs on all the I/O Banks.

MachXO1200 and MachXO2280 devices contain two types of sysIO buffer pairs.

1. Top and Bottom sysIO Buffer Pairs

The sysIO buffer pairs in the top and bottom Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (for ratioed or absolute input levels). The I/O pairs on the top and bottom

Table 2-10. Supported Output Standards

Output Standard	Drive	V _{CCIO} (Typ.)
Single-ended Interfaces		
LVTTTL	4mA, 8mA, 12mA, 16mA	3.3
LVC MOS33	4mA, 8mA, 12mA, 14mA	3.3
LVC MOS25	4mA, 8mA, 12mA, 14mA	2.5
LVC MOS18	4mA, 8mA, 12mA, 14mA	1.8
LVC MOS15	4mA, 8mA	1.5
LVC MOS12	2mA, 6mA	1.2
LVC MOS33, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS25, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS18, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS15, Open Drain	4mA, 8mA	—
LVC MOS12, Open Drain	2mA, 6mA	—
PCI33 ³	N/A	3.3
Differential Interfaces		
LVDS ^{1, 2}	N/A	2.5
BLVDS, RSDS ²	N/A	2.5
LVPECL ²	N/A	3.3

1. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers.

2. These interfaces can be emulated with external resistors in all devices.

3. Top Banks of MachXO1200 and MachXO2280 devices only.

sysIO Buffer Banks

The number of Banks vary between the devices of this family. Eight Banks surround the two larger devices, the MachXO1200 and MachXO2280 (two Banks per side). The MachXO640 has four Banks (one Bank per side). The smallest member of this family, the MachXO256, has only two Banks.

Each sysIO buffer Bank is capable of supporting multiple I/O standards. Each Bank has its own I/O supply voltage (V_{CCIO}) which allows it to be completely independent from the other Banks. Figure 2-18, Figure 2-18, Figure 2-20 and Figure 2-21 shows the sysIO Banks and their associated supplies for all devices.

the system. These capabilities make the MachXO ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The MachXO “C” devices ($V_{CC} = 1.8/2.5/3.3V$) have a sleep mode that allows standby current to be reduced dramatically during periods of system inactivity. Entry and exit to Sleep mode is controlled by the SLEEPN pin.

During Sleep mode, the logic is non-operational, registers and EBR contents are not maintained, and I/Os are tri-stated. Do not enter Sleep mode during device programming or configuration operation. In Sleep mode, power supplies are in their normal operating range, eliminating the need for external switching of power supplies. Table 2-11 compares the characteristics of Normal, Off and Sleep modes.

Table 2-11. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static Icc	Typical <10mA	0	Typical <100uA
I/O Leakage	<10μA	<1mA	<10μA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	0	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up, along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to VCC is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically, the device enters sleep mode several hundred nanoseconds after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet shows a detailed timing diagram.

Oscillator

Every MachXO device has an internal CMOS oscillator. The oscillator can be routed as an input clock to the clock tree or to general routing resources. The oscillator frequency can be divided by internal logic. There is a dedicated programming bit to enable/disable the oscillator. The oscillator frequency ranges from 18MHz to 26MHz.

Configuration and Testing

The following section describes the configuration and testing features of the MachXO family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All MachXO devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port shares its power supply with one of the VCCIO Banks (MachXO256: V_{CCIO1} ; MachXO640: V_{CCIO2} ; MachXO1200 and MachXO2280: V_{CCIO5}) and can operate with LVCMOS3.3, 2.5, 1.8, 1.5, and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All MachXO devices contain a test access port that can be used for device configuration and programming.

The non-volatile memory in the MachXO can be configured in two different modes:

- In IEEE 1532 mode via the IEEE 1149.1 port. In this mode, the device is off-line and I/Os are controlled by BSCAN registers.
- In background mode via the IEEE 1149.1 port. This allows the device to remain operational in user mode while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- After a refresh command is issued via the IEEE 1149.1 port.
- In IEEE 1532 mode via the IEEE 1149.1 port.

Figure 2-22 provides a pictorial representation of the different programming modes available in the MachXO devices. On power-up, the SRAM is ready to be configured with IEEE 1149.1 serial TAP port using IEEE 1532 protocols.

Leave Alone I/O

When using IEEE 1532 mode for non-volatile memory programming, SRAM configuration, or issuing a refresh command, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reconfiguration or reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#) for details.

Security

The MachXO devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear the security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

MachXO External Switching Characteristics¹

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Global Clock without PLL) ¹									
t _{PD}	Best Case t _{PD} Through 1 LUT	LCMXO256	—	3.5	—	4.2	—	4.9	ns
		LCMXO640	—	3.5	—	4.2	—	4.9	ns
		LCMXO1200	—	3.6	—	4.4	—	5.1	ns
		LCMXO2280	—	3.6	—	4.4	—	5.1	ns
t _{CO}	Best Case Clock to Output - From PFU	LCMXO256	—	4.0	—	4.8	—	5.6	ns
		LCMXO640	—	4.0	—	4.8	—	5.7	ns
		LCMXO1200	—	4.3	—	5.2	—	6.1	ns
		LCMXO2280	—	4.3	—	5.2	—	6.1	ns
t _{SU}	Clock to Data Setup - To PFU	LCMXO256	1.3	—	1.6	—	1.8	—	ns
		LCMXO640	1.1	—	1.3	—	1.5	—	ns
		LCMXO1200	1.1	—	1.3	—	1.6	—	ns
		LCMXO2280	1.1	—	1.3	—	1.5	—	ns
t _H	Clock to Data Hold - To PFU	LCMXO256	-0.3	—	-0.3	—	-0.3	—	ns
		LCMXO640	-0.1	—	-0.1	—	-0.1	—	ns
		LCMXO1200	0.0	—	0.0	—	0.0	—	ns
		LCMXO2280	-0.4	—	-0.4	—	-0.4	—	ns
f _{MAX_IO}	Clock Frequency of I/O and PFU Register	LCMXO256	—	600	—	550	—	500	MHz
		LCMXO640	—	600	—	550	—	500	MHz
		LCMXO1200	—	600	—	550	—	500	MHz
		LCMXO2280	—	600	—	550	—	500	MHz
t _{SKEW_PRI}	Global Clock Skew Across Device	LCMXO256	—	200	—	220	—	240	ps
		LCMXO640	—	200	—	220	—	240	ps
		LCMXO1200	—	220	—	240	—	260	ps
		LCMXO2280	—	220	—	240	—	260	ps

1. General timing numbers based on LVCMOS2.5V, 12 mA.
Rev. A 0.19

MachXO Family Timing Adders^{1, 2, 3}

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25 ⁴	LVDS	0.44	0.53	0.61	ns
BLVDS25 ⁴	BLVDS	0.44	0.53	0.61	ns
LVPECL33 ⁴	LVPECL	0.42	0.50	0.59	ns
LVTTTL33	LVTTTL	0.01	0.01	0.01	ns
LVC MOS33	LVC MOS 3.3	0.01	0.01	0.01	ns
LVC MOS25	LVC MOS 2.5	0.00	0.00	0.00	ns
LVC MOS18	LVC MOS 1.8	0.07	0.08	0.10	ns
LVC MOS15	LVC MOS 1.5	0.14	0.17	0.19	ns
LVC MOS12	LVC MOS 1.2	0.40	0.48	0.56	ns
PCI33 ⁴	PCI	0.01	0.01	0.01	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	-0.13	-0.15	-0.18	ns
LVDS25 ⁴	LVDS 2.5	-0.21	-0.26	-0.30	ns
BLVDS25	BLVDS 2.5	-0.03	-0.03	-0.04	ns
LVPECL33	LVPECL 3.3	0.04	0.04	0.05	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.04	0.04	0.05	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.06	0.07	0.08	ns
LVTTTL33_12mA	LVTTTL 12mA drive	-0.01	-0.01	-0.01	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.50	0.60	0.70	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.04	0.04	0.05	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.06	0.07	0.08	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	-0.01	-0.01	-0.01	ns
LVC MOS33_14mA	LVC MOS 3.3 14mA drive	0.50	0.60	0.70	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.05	0.06	0.07	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.10	0.12	0.13	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVC MOS25_14mA	LVC MOS 2.5 14mA drive	0.34	0.40	0.47	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.11	0.13	0.15	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.05	0.06	0.06	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	-0.06	-0.07	-0.08	ns
LVC MOS18_14mA	LVC MOS 1.8 14mA drive	0.06	0.07	0.09	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.15	0.19	0.22	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.05	0.06	0.07	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.26	0.31	0.36	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.05	0.06	0.07	ns
PCI33 ⁴	PCI33	1.85	2.22	2.59	ns

1. Timing adders are characterized but not tested on every device.

2. LVC MOS timing is measured with the load specified in Switching Test Conditions table.

3. All other standards tested according to the appropriate specifications.

4. I/O standard only available in LCMXO1200 and LCMXO2280 devices.

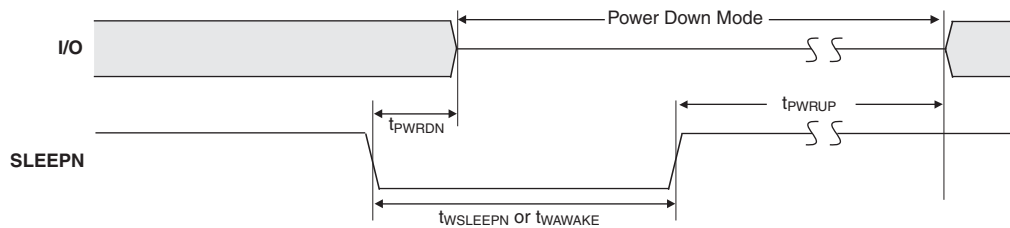
Rev. A 0.19

MachXO “C” Sleep Mode Timing

Symbol	Parameter	Device	Min.	Typ.	Max	Units
t_{PWRDN}	SLEEPN Low to Power Down	All	—	—	400	ns
t_{PWRUP}	SLEEPN High to Power Up	LCMXO256	—	—	400	μs
		LCMXO640	—	—	600	μs
		LCMXO1200	—	—	800	μs
		LCMXO2280	—	—	1000	μs
$t_{WSLEEPN}$	SLEEPN Pulse Width	All	400	—	—	ns
t_{WAWAKE}	SLEEPN Pulse Rejection	All	—	—	100	ns

Rev. A 0.19

Flash Download Time



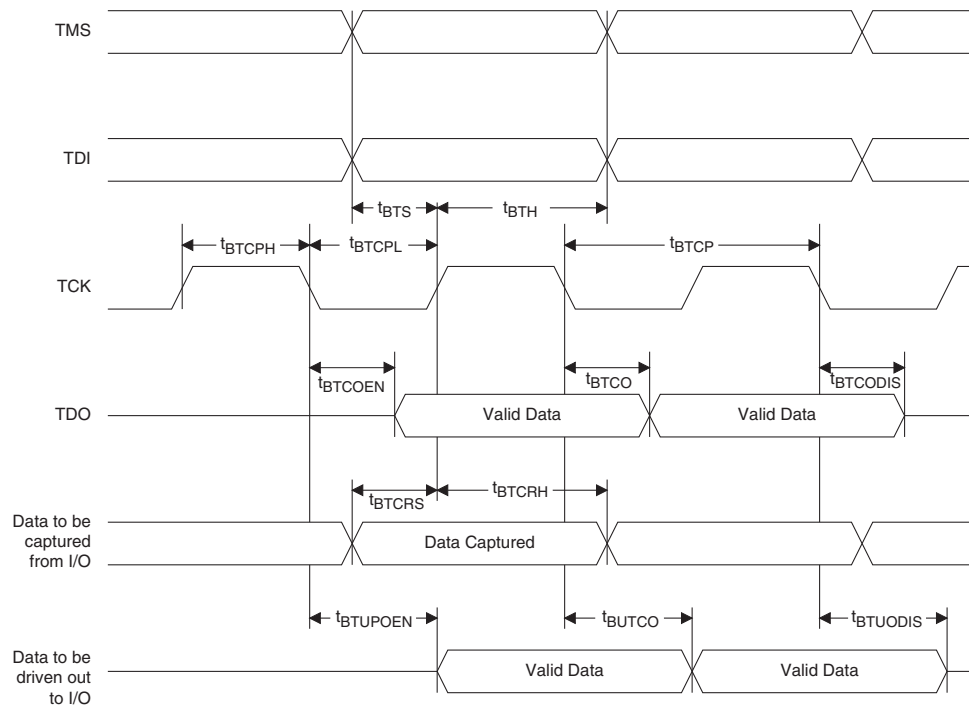
Symbol	Parameter	Min.	Typ.	Max.	Units
$t_{REFRESH}$	Minimum V_{CC} or V_{CCAUX} (later of the two supplies) to Device I/O Active	LCMXO256	—	0.4	ms
		LCMXO640	—	0.6	ms
		LCMXO1200	—	0.8	ms
		LCMXO2280	—	1.0	ms

JTAG Port Timing Specifications

Symbol	Parameter	Min.	Max.	Units
f_{MAX}	TCK [BSCAN] clock frequency	—	25	MHz
t_{BTCP}	TCK [BSCAN] clock pulse width	40	—	ns
t_{BTCPH}	TCK [BSCAN] clock pulse width high	20	—	ns
t_{BTCPL}	TCK [BSCAN] clock pulse width low	20	—	ns
t_{BTS}	TCK [BSCAN] setup time	8	—	ns
t_{BTH}	TCK [BSCAN] hold time	10	—	ns
t_{BTRF}	TCK [BSCAN] rise/fall time	50	—	mV/ns
t_{BTCO}	TAP controller falling edge of clock to output valid	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to output disabled	—	10	ns
t_{BTCOEN}	TAP controller falling edge of clock to output enabled	—	10	ns
t_{BTCRS}	BSCAN test capture register setup time	8	—	ns
t_{BTCRH}	BSCAN test capture register hold time	25	—	ns
t_{BUTCO}	BSCAN test update register, falling edge of clock to output valid	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to output disabled	—	25	ns
$t_{BTUPOEN}$	BSCAN test update register, falling edge of clock to output enabled	—	25	ns

Rev. A 0.19

Figure 3-5. JTAG Port Timing Waveforms



Power Supply and NC

Signal	100 TQFP ¹	144 TQFP ¹	100 csBGA ²
VCC	LCMXO256/640: 35, 90 LCMXO1200/2280: 17, 35, 66, 91	21, 52, 93, 129	P7, B6
VCCIO0	LCMXO256: 60, 74, 92 LCMXO640: 80, 92 LCMXO1200/2280: 94	LCMXO640: 117, 135 LCMXO1200/2280: 135	LCMXO256: H14, A14, B5 LCMXO640: B12, B5
VCCIO1	LCMXO256: 10, 24, 41 LCMXO640: 60, 74 LCMXO1200/2280: 80	LCMXO640: 82, 98 LCMXO1200/2280: 117	LCMXO256: G1, P1, P10 LCMXO640: H14, A14
VCCIO2	LCMXO256: None LCMXO640: 29, 41 LCMXO1200/2280: 70	LCMXO640: 38, 63 LCMXO1200/2280: 98	LCMXO256: None LCMXO640: P4, P10
VCCIO3	LCMXO256: None LCMXO640: 10, 24 LCMXO1200/2280: 56	LCMXO640: 10, 26 LCMXO1200/2280: 82	LCMXO256: None LCMXO640: G1, P1
VCCIO4	LCMXO256/640: None LCMXO1200/2280: 44	LCMXO640: None LCMXO1200/2280: 63	—
VCCIO5	LCMXO256/640: None LCMXO1200/2280: 27	LCMXO640: None LCMXO1200/2280: 38	—
VCCIO6	LCMXO256/640: None LCMXO1200/2280: 20	LCMXO640: None LCMXO1200/2280: 26	—
VCCIO7	LCMXO256/640: None LCMXO1200/2280: 6	LCMXO640: None LCMXO1200/2280: 10	—
VCCAUX	LCMXO256/640: 88 LCMXO1200/2280: 36, 90	53, 128	B7
GND ³	LCMXO256: 40, 84, 62, 75, 93, 12, 25, 42 LCMXO640: 40, 84, 81, 93, 62, 75, 30, 42, 12, 25 LCMXO1200/2280: 9, 41, 59, 83, 100, 76, 50, 26	16, 59, 88, 123, 118, 136, 83, 99, 37, 64, 11, 27	LCMXO256: N9, B9, G14, B13, A4, H1, N2, N10 LCMXO640: N9, B9, A10, A4, G14, B13, N3, N10, H1, N2
NC ⁴			—

1. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
2. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
3. All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
4. NC pins should not be connected to any active signals, VCC or GND.

LCMXO256 and LCMXO640 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMXO256				LCMXO640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
85	PT4B	0	PCLK0_1**	C	PT6B	0	PCLK0_1**	
86	PT4A	0	PCLK0_0**	T	PT5B	0	PCLK0_0**	C
87	PT3D	0		C	PT5A	0		T
88	VCCAUX	-			VCCAUX	-		
89	PT3C	0		T	PT4F	0		
90	VCC	-			VCC	-		
91	PT3B	0		C	PT3F	0		
92	VCCIO0	0			VCCIO0	0		
93	GNDIO0	0			GNDIO0	0		
94	PT3A	0		T	PT3B	0		C
95	PT2F	0		C	PT3A	0		T
96	PT2E	0		T	PT2F	0		C
97	PT2D	0		C	PT2E	0		T
98	PT2C	0		T	PT2B	0		C
99	PT2B	0		C	PT2C	0		
100	PT2A	0		T	PT2A	0		T

* NC for "E" devices.

** Primary clock inputs are single-ended.

LCMX01200 and LCMX02280 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMX01200				LCMX02280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
42	PB9A	4		T	PB12A	4		T
43	PB9B	4		C	PB12B	4		C
44	VCCIO4	4			VCCIO4	4		
45	PB10A	4		T	PB13A	4		T
46	PB10B	4		C	PB13B	4		C
47***	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
48	PB11A	4		T	PB16A	4		T
49	PB11B	4		C	PB16B	4		C
50**	GNDIO3 GNDIO4	-			GNDIO3 GNDIO4	-		
51	PR16B	3			PR19B	3		
52	PR15B	3		C*	PR18B	3		C*
53	PR15A	3		T*	PR18A	3		T*
54	PR14B	3		C*	PR17B	3		C*
55	PR14A	3		T*	PR17A	3		T*
56	VCCIO3	3			VCCIO3	3		
57	PR12B	3		C*	PR15B	3		C*
58	PR12A	3		T*	PR15A	3		T*
59	GND	-			GND	-		
60	PR10B	3		C*	PR13B	3		C*
61	PR10A	3		T*	PR13A	3		T*
62	PR9B	3		C*	PR11B	3		C*
63	PR9A	3		T*	PR11A	3		T*
64	PR8B	2		C*	PR10B	2		C*
65	PR8A	2		T*	PR10A	2		T*
66	VCC	-			VCC	-		
67	PR6C	2			PR8C	2		
68	PR6B	2		C*	PR8B	2		C*
69	PR6A	2		T*	PR8A	2		T*
70	VCCIO2	2			VCCIO2	2		
71	PR4D	2			PR5D	2		
72	PR4B	2		C*	PR5B	2		C*
73	PR4A	2		T*	PR5A	2		T*
74	PR2B	2		C	PR3B	2		C*
75	PR2A	2		T	PR3A	2		T*
76**	GNDIO1 GNDIO2	-			GNDIO1 GNDIO2	-		
77	PT11C	1			PT15C	1		
78	PT11B	1		C	PT14B	1		C
79	PT11A	1		T	PT14A	1		T
80	VCCIO1	1			VCCIO1	1		
81	PT9E	1			PT12D	1		C

LCMX0256 and LCMX0640 Logic Signal Connections: 100 csBGA (Cont.)

LCMX0256					LCMX0640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
A4	GNDIO0	0			A4	GNDIO0	0		
B4	PT3A	0		T	B4	PT3B	0		C
A3	PT2F	0		C	A3	PT3A	0		T
B3	PT2E	0		T	B3	PT2F	0		C
A2	PT2D	0		C	A2	PT2E	0		T
C3	PT2C	0		T	C3	PT2B	0		C
A1	PT2B	0		C	A1	PT2C	0		
B2	PT2A	0		T	B2	PT2A	0		T
N9	GND	-			N9	GND	-		
B9	GND	-			B9	GND	-		
B5	VCCIO0	0			B5	VCCIO0	0		
A14	VCCIO0	0			A14	VCCIO1	1		
H14	VCCIO0	0			H14	VCCIO1	1		
P10	VCCIO1	1			P10	VCCIO2	2		
G1	VCCIO1	1			G1	VCCIO3	3		
P1	VCCIO1	1			P1	VCCIO3	3		

*NC for "E" devices.

**Primary clock inputs are single-ended.

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 132 csBGA

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B1	PL2A	3		T	B1	PL2A	7		T	B1	PL2A	7	LUM0_PLLT_FB_A	T
C1	PL2B	3		C	C1	PL3C	7		T	C1	PL3C	7	LUM0_PLLT_IN_A	T
B2	PL2C	3		T	B2	PL2B	7		C	B2	PL2B	7	LUM0_PLLC_FB_A	C
C2	PL2D	3		C	C2	PL4A	7		T*	C2	PL4A	7		T*
C3	PL3A	3		T	C3	PL3D	7		C	C3	PL3D	7	LUM0_PLLC_IN_A	C
D1	PL3B	3		C	D1	PL4B	7		C*	D1	PL4B	7		C*
D3	PL3D	3			D3	PL4C	7			D3	PL4C	7		
E1	GNDIO3	3			E1	GNDIO7	7			E1	GNDIO7	7		
E2	PL5A	3		T	E2	PL6A	7		T*	E2	PL7A	7		T*
E3	PL5B	3	GSRN	C	E3	PL6B	7	GSRN	C*	E3	PL7B	7	GSRN	C*
F2	PL5D	3			F2	PL6D	7			F2	PL7D	7		
F3	PL6B	3			F3	PL7C	7		T	F3	PL9C	7		T
G1	PL6C	3		T	G1	PL7D	7		C	G1	PL9D	7		C
G2	PL6D	3		C	G2	PL8C	7		T	G2	PL10C	7		T
G3	PL7A	3		T	G3	PL8D	7		C	G3	PL10D	7		C
H2	PL7B	3		C	H2	PL10A	6		T*	H2	PL12A	6		T*
H1	PL7C	3			H1	PL10B	6		C*	H1	PL12B	6		C*
H3	VCC	-			H3	VCC	-			H3	VCC	-		
J1	PL8A	3			J1	PL11B	6			J1	PL14D	6		C
J2	PL8C	3	TSALL		J2	PL11C	6	TSALL	T	J2	PL14C	6	TSALL	T
J3	PL9A	3		T	J3	PL11D	6		C	J3	PL14B	6		
K2	PL9B	3		C	K2	PL12A	6		T*	K2	PL15A	6		T*
K1	PL9C	3			K1	PL12B	6		C*	K1	PL15B	6		C*
L2	GNDIO3	3			L2	GNDIO6	6			L2	GNDIO6	6		
L1	PL10A	3		T	L1	PL14A	6	LLM0_PLLT_FB_A	T*	L1	PL17A	6	LLM0_PLLT_FB_A	T*
L3	PL10B	3		C	L3	PL14B	6	LLM0_PLLC_FB_A	C*	L3	PL17B	6	LLM0_PLLC_FB_A	C*
M1	PL11A	3		T	M1	PL15A	6	LLM0_PLLT_IN_A	T*	M1	PL18A	6	LLM0_PLLT_IN_A	T*
N1	PL11B	3		C	N1	PL16A	6		T	N1	PL19A	6		T
M2	PL11C	3		T	M2	PL15B	6	LLM0_PLLC_IN_A	C*	M2	PL18B	6	LLM0_PLLC_IN_A	C*
P1	PL11D	3		C	P1	PL16B	6		C	P1	PL19B	6		C
P2	GNDIO2	2			P2	GNDIO5	5			P2	GNDIO5	5		
P3	TMS	2	TMS		P3	TMS	5	TMS		P3	TMS	5	TMS	
M3	PB2C	2		T	M3	PB2C	5		T	M3	PB2A	5		T
N3	PB2D	2		C	N3	PB2D	5		C	N3	PB2B	5		C
P4	TCK	2	TCK		P4	TCK	5	TCK		P4	TCK	5	TCK	
M4	PB3B	2			M4	PB3B	5			M4	PB3B	5		
N4	PB3C	2		T	N4	PB4A	5		T	N4	PB4A	5		T
P5	PB3D	2		C	P5	PB4B	5		C	P5	PB4B	5		C
N5	TDO	2	TDO		N5	TDO	5	TDO		N5	TDO	5	TDO	
M5	TDI	2	TDI		M5	TDI	5	TDI		M5	TDI	5	TDI	
N6	PB4E	2		T	N6	PB5C	5			N6	PB6C	5		
P6	VCC	-			P6	VCC	-			P6	VCC	-		
M6	PB4F	2		C	M6	PB6A	5			M6	PB8A	5		
P7	VCCAUX	-			P7	VCCAUX	-			P7	VCCAUX	-		
N7	PB5A	2		T	N7	PB6F	5			N7	PB8F	5		
M7	PB5B	2	PCLK2_1***	C	M7	PB7B	4	PCLK4_1***		M7	PB10F	4	PCLK4_1***	
N8	PB5D	2			N8	PB7C	4		T	N8	PB10C	4		T
P8	PB6A	2		T	P8	PB7D	4		C	P8	PB10D	4		C
M8	PB6B	2	PCLK2_0***	C	M8	PB7F	4	PCLK4_0***		M8	PB10B	4	PCLK4_0***	
N9	PB7A	2		T	N9	PB9A	4		T	N9	PB12A	4		T

LCMX0640, LCMX01200 and LCMX02280 Logic Signal Connections: 132 csBGA (Cont.)

LCMX0640					LCMX01200					LCMX02280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
M9	PB7B	2		C	M9	PB9B	4		C	M9	PB12B	4		C
N10	PB7E	2		T	N10	PB9C	4		T	N10	PB12C	4		T
P10	PB7F	2		C	P10	PB9D	4		C	P10	PB12D	4		C
N11	GNDIO2	2			N11	GNDIO4	4			N11	GNDIO4	4		
P11	PB8C	2		T	P11	PB10A	4		T	P11	PB13C	4		T
M11	PB8D	2		C	M11	PB10B	4		C	M11	PB13D	4		C
P12	PB9C	2		T	P12	PB10C	4			P12	PB15B	4		
P13	PB9D	2		C	P13	PB11C	4		T	P13	PB16C	4		T
N12**	SLEEPN	-	SLEEPN		N12**	SLEEPN	-	SLEEPN		N12**	SLEEPN	-	SLEEPN	
P14	PB9F	2			P14	PB11D	4		C	P14	PB16D	4		C
N14	PR11D	1		C	N14	PR16B	3		C	N14	PR19B	3		C
M14	PR11C	1		T	M14	PR15B	3		C*	M14	PR18B	3		C*
N13	PR11B	1		C	N13	PR16A	3		T	N13	PR19A	3		T
M12	PR11A	1		T	M12	PR15A	3		T*	M12	PR18A	3		T*
M13	PR10B	1		C	M13	PR14B	3		C*	M13	PR17B	3		C*
L14	PR10A	1		T	L14	PR14A	3		T*	L14	PR17A	3		T*
L13	GNDIO1	1			L13	GNDIO3	3			L13	GNDIO3	3		
K14	PR8D	1		C	K14	PR12B	3		C*	K14	PR15B	3		C*
K13	PR8C	1		T	K13	PR12A	3		T*	K13	PR15A	3		T*
K12	PR8B	1		C	K12	PR11B	3		C*	K12	PR14B	3		C*
J13	PR8A	1		T	J13	PR11A	3		T*	J13	PR14A	3		T*
J12	PR7C	1			J12	PR10B	3		C*	J12	PR13B	3		C*
H14	PR7B	1		C	H14	PR10A	3		T*	H14	PR13A	3		T*
H13	PR7A	1		T	H13	PR9B	3		C*	H13	PR11B	3		C*
H12	PR6D	1		C	H12	PR9A	3		T*	H12	PR11A	3		T*
G13	PR6C	1		T	G13	PR8B	2		C*	G13	PR10B	2		C*
G14	PR6B	1			G14	PR8A	2		T*	G14	PR10A	2		T*
G12	VCC	-			G12	VCC	-			G12	VCC	-		
F14	PR5D	1		C	F14	PR6C	2			F14	PR8C	2		
F13	PR5C	1		T	F13	PR6B	2		C*	F13	PR8B	2		C*
F12	PR4D	1		C	F12	PR6A	2		T*	F12	PR8A	2		T*
E13	PR4C	1		T	E13	PR5B	2		C*	E13	PR7B	2		C*
E14	PR4B	1			E14	PR5A	2		T*	E14	PR7A	2		T*
D13	GNDIO1	1			D13	GNDIO2	2			D13	GNDIO2	2		
D14	PR3D	1		C	D14	PR4B	2		C*	D14	PR5B	2		C*
D12	PR3C	1		T	D12	PR4A	2		T*	D12	PR5A	2		T*
C14	PR2D	1		C	C14	PR3D	2		C	C14	PR4D	2		C
B14	PR2C	1		T	B14	PR2B	2		C	B14	PR3B	2		C*
C13	PR2B	1		C	C13	PR3C	2		T	C13	PR4C	2		T
A14	PR2A	1		T	A14	PR2A	2		T	A14	PR3A	2		T*
A13	PT9F	0		C	A13	PT11D	1		C	A13	PT16D	1		C
A12	PT9E	0		T	A12	PT11B	1		C	A12	PT16B	1		C
B13	PT9D	0		C	B13	PT11C	1		T	B13	PT16C	1		T
B12	PT9C	0		T	B12	PT10F	1			B12	PT15D	1		
C12	PT9B	0		C	C12	PT11A	1		T	C12	PT16A	1		T
A11	PT9A	0		T	A11	PT10D	1		C	A11	PT14B	1		C
C11	PT8C	0			C11	PT10C	1		T	C11	PT14A	1		T
A10	GNDIO0	0			A10	GNDIO1	1			A10	GNDIO1	1		
B10	PT7F	0		C	B10	PT9F	1		C	B10	PT12F	1		C
C10	PT7E	0		T	C10	PT9E	1		T	C10	PT12E	1		T

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
51	TDI	2	TDI		TDI	5	TDI		TDI	5	TDI	
52	VCC	-			VCC	-			VCC	-		
53	VCCAUX	-			VCCAUX	-			VCCAUX	-		
54	PB5A	2		T	PB6F	5			PB8F	5		
55	PB5B	2	PCLKT2_1***	C	PB7B	4	PCLK4_1***		PB10F	4	PCLK4_1***	
56	PB5D	2			PB7C	4		T	PB10C	4		T
57	PB6A	2		T	PB7D	4		C	PB10D	4		C
58	PB6B	2	PCLKT2_0***	C	PB7F	4	PCLK4_0***		PB10B	4	PCLK4_0***	
59	GND	-			GND	-			GND	-		
60	PB7C	2			PB9A	4		T	PB12A	4		T
61	PB7E	2			PB9B	4		C	PB12B	4		C
62	PB8A	2			PB9E	4			PB12E	4		
63	VCCIO2	2			VCCIO4	4			VCCIO4	4		
64	GNDIO2	2			GNDIO4	4			GNDIO4	4		
65	PB8C	2		T	PB10A	4		T	PB13A	4		T
66	PB8D	2		C	PB10B	4		C	PB13B	4		C
67	PB9A	2		T	PB10C	4		T	PB13C	4		T
68	PB9C	2		T	PB10D	4		C	PB13D	4		C
69	PB9B	2		C	PB10F	4			PB14D	4		
70**	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
71	PB9D	2		C	PB11C	4		T	PB16C	4		T
72	PB9F	2			PB11D	4		C	PB16D	4		C
73	PR11D	1		C	PR16B	3		C	PR20B	3		C
74	PR11B	1		C	PR16A	3		T	PR20A	3		T
75	PR11C	1		T	PR15B	3		C*	PR19B	3		C
76	PR10D	1		C	PR15A	3		T*	PR19A	3		T
77	PR11A	1		T	PR14D	3		C	PR17D	3		C
78	PR10B	1		C	PR14C	3		T	PR17C	3		T
79	PR10C	1		T	PR14B	3		C*	PR17B	3		C*
80	PR10A	1		T	PR14A	3		T*	PR17A	3		T*
81	PR9D	1			PR13D	3			PR16D	3		
82	VCCIO1	1			VCCIO3	3			VCCIO3	3		
83	GNDIO1	1			GNDIO3	3			GNDIO3	3		
84	PR9A	1			PR12B	3		C*	PR15B	3		C*
85	PR8C	1			PR12A	3		T*	PR15A	3		T*
86	PR8A	1			PR11B	3		C*	PR14B	3		C*
87	PR7D	1			PR11A	3		T*	PR14A	3		T*
88	GND	-			GND	-			GND	-		
89	PR7B	1		C	PR10B	3		C*	PR13B	3		C*
90	PR7A	1		T	PR10A	3		T*	PR13A	3		T*
91	PR6D	1		C	PR8B	2		C*	PR10B	2		C*
92	PR6C	1		T	PR8A	2		T*	PR10A	2		T*
93	VCC	-			VCC	-			VCC	-		
94	PR5D	1			PR6B	2		C*	PR8B	2		C*
95	PR5B	1			PR6A	2		T*	PR8A	2		T*
96	PR4D	1			PR5B	2		C*	PR7B	2		C*
97	PR4B	1		C	PR5A	2		T*	PR7A	2		T*
98	VCCIO1	1			VCCIO2	2			VCCIO2	2		
99	GNDIO1	1			GNDIO2	2			GNDIO2	2		
100	PR4A	1		T	PR4C	2			PR5C	2		

LCMX02280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMX02280				
Ball Number	Ball Function	Bank	Dual Function	Differential
T2	PL20B	6		C
P6	TMS	5	TMS	
V1	PB2A	5		T
U2	PB2B	5		C
T3	PB2C	5		T
N7	TCK	5	TCK	
R4	PB2D	5		C
R5	PB3A	5		T
T4	PB3B	5		C
VCC	VCC	-		
R6	PB3C	5		T
P7	PB3D	5		C
U3	PB4A	5		T
T5	PB4B	5		C
V2	PB4C	5		T
N8	TDO	5	TDO	
V3	PB4D	5		C
T6	PB5A	5		T
GND	GNDIO5	5		
VCCIO5	VCCIO5	5		
U4	PB5B	5		C
P8	PB5C	5		T
T7	PB5D	5		C
V4	TDI	5	TDI	
R8	PB6A	5		T
N9	PB6B	5		C
U5	PB6C	5		T
V5	PB6D	5		C
U6	PB7A	5		T
VCC	VCC	-		
V6	PB7B	5		C
P9	PB7C	5		T
T8	PB7D	5		C
U7	PB8A	5		T
V7	PB8B	5		C
M10	VCCAUX	-		
U8	PB8C	5		T
V8	PB8D	5		C
VCCIO5	VCCIO5	5		
GND	GNDIO5	5		
T9	PB8E	5		T
U9	PB8F	5		C
V9	PB9A	4		T

LCMX02280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMX02280				
Ball Number	Ball Function	Bank	Dual Function	Differential
A10	PT8E	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
A9	PT8D	0		C
C9	PT8C	0		T
B9	PT8B	0		C
F9	VCCAUX	-		
A8	PT8A	0		T
B8	PT7D	0		C
C8	PT7C	0		T
VCC	VCC	-		
A7	PT7B	0		C
B7	PT7A	0		T
A6	PT6A	0		T
B6	PT6B	0		C
D8	PT6C	0		T
F8	PT6D	0		C
C7	PT6E	0		T
E8	PT6F	0		C
D7	PT5D	0		C
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E7	PT5C	0		T
A5	PT5B	0		C
C6	PT5A	0		T
B5	PT4A	0		T
A4	PT4B	0		C
D6	PT4C	0		T
F7	PT4D	0		C
B4	PT4E	0		T
GND	GND	-		
C5	PT4F	0		C
F6	PT3D	0		C
E5	PT3C	0		T
E6	PT3B	0		C
D5	PT3A	0		T
A3	PT2D	0		C
C4	PT2C	0		T
A2	PT2B	0		C
B2	PT2A	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E14	GND	-		

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the [Thermal Management](#) document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following:

- [Thermal Management](#) document
- TN1090 - [Power Estimation and Management for MachXO Devices](#)
- Power Calculator tool included with the Lattice ispLEVER design tool, or as a standalone download from www.latticesemi.com/software